TOSHIBA Field Effect Transistor Silicon P, N Channel MOS Type (U-MOS IV / U-MOS III)

TPCF8402

Portable Equipment Applications Motor Drive Applications DC-DC Converter Applications

Low drain-source ON resistance : P Channel R_{DS} (ON) = 60 m Ω (typ.)

N Channel R_{DS} (ON) = 38 m Ω (typ.)

High forward transfer admittance : P Channel $|Y_{fs}| = 5.9 \text{ S}$ (typ.)

N Channel $|Y_{fs}| = 6.8 \text{ S (typ.)}$

Low leakage current : P Channel $I_{DSS} = -10 \mu A (V_{DS} = -30 \text{ V})$

N Channel $I_{DSS} = 10 \mu A (V_{DS} = 30 V)$

Enhancement-mode

: P Channel $V_{th} = -0.8$ to $-2.0 \text{ V} (V_{DS} = -10 \text{ V}, I_D = -1 \text{mA})$

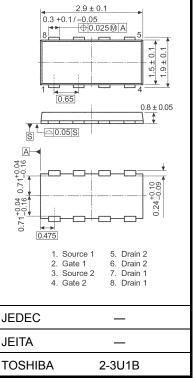
N Channel $V_{th} = 1.3 \text{ to } 2.5 \text{ V } (V_{DS} = 10 \text{ V}, I_D = 1 \text{mA})$

Absolute Maximum Ratings (Ta = 25°C)

Cł	Symbol	Rating		Unit		
Drain-source v	V_{DSS}	-30	30	V		
Drain-gate volt	tage ($R_{GS} = 20 \text{ k}\Omega$)	V_{DGR}	-30	30	V	
Gate-source v	oltage	V_{GSS}	±20	±20	V	
Drain current	DC (Note 1)	I _D	-3.2	4.0	А	
Diam current	Pulse (Note 1)	I_{DP}	-12.8	16.0	^	
Drain power dissipation	Single-device operation (Note 3a)	P _{D (1)}	1.35	1.35		
(t = 5 s) (Note 2a)	Single-device value at dual operation (Note 3b)	P _{D (2)}	1.12	1.12	W	
Drain power dissipation (t = 5 s) (Note 2b)	Single-device operation (Note 3a)	P _{D (1)}	0.53	0.53	VV	
	Single-device value at dual operation (Note 3b)	P _{D (2)}	0.33	0.33		
Single pulse a	valanche energy (Note 4)	E _{AS}	0.67	2.6	mJ	
Avalanche cur	rent	I _{AR}	-1.6	2.0	Α	
Repetitive avalanche energy Single-device value at dual operation (Note 2a, 3b, 5)		E _{AR}	0.11		mJ	
Channel temperature		T _{ch}	150		°C	
Storage tempe	erature range	T _{stg}	-55 to 150		°C	

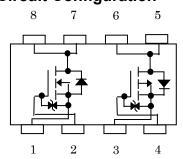
 2.9 ± 0.1

Unit: mm



Weight: 0.011 g (typ.)

Circuit Configuration



Note: For Notes 1 to 5, refer to the next page.

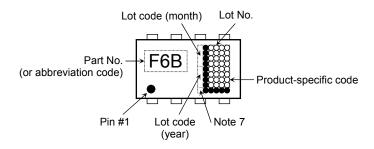
Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

This transistor is an electrostatic-sensitive device. Handle with caution.

Thermal Characteristics

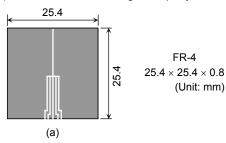
Charac	Symbol	Max	Unit		
Thermal resistance, channel to ambient (t = 5 s) (Note 2a)	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	92.6	°C/W	
	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	111.6		
Thermal resistance, channel to ambient	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	235.8	°C/W	
(t = 5 s) (Note 2b)	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	378.8	C/VV	

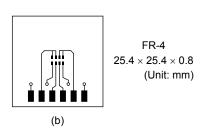
Marking (Note 6)



Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (b) Device mounted on a glass-epoxy board (b)





Note 3: a) The power dissipation and thermal resistance values are shown for a single device. (During single-device operation, power is only applied to one device.)

b) The power dissipation and thermal resistance values are shown for a single device. (During dual operation, power is evenly applied to both devices.)

Note 4: P Channel: $V_{DD}=-24$ V, $T_{ch}=25^{\circ}$ C (initial), L=0.2 mH, $R_{G}=25$ Ω , $I_{AR}=-1.6$ A N Channel: $V_{DD}=24$ V, $T_{ch}=25^{\circ}$ C (initial), L=0.5 mH, $R_{G}=25$ Ω , $I_{AR}=2.0$ A

Note 5: Repetitive rating: Pulse width limited by maximum channel temperature.

Note 6: "●" on the lower left of the marking indicates Pin 1.

Note 7 A dot marking identifies the indication of product Labels.

Without a dot: [[Pb]]/INCLUDES > MCV

With a dot: [[G]]/RoHS COMPATIBLE or [[G]]/RoHS [[Pb]]

Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product. The RoHS is the Directive 2002/95/EC of the European Parliament and of the Council of 27 January 2003 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.



Electrical Characteristics (Ta = 25°C)

Ch	aracteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I _{GSS}	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μА
Drain cut-off curr	ent	I _{DSS}	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	-10	μА
Drain-source bre	akdown voltage	V _{(BR)DSS}	$I_D = -10$ mA, $V_{GS} = 0$ V	-30	_	_	· /
Drain-source breakdown voltage		V _{(BR)DSX}	$I_D = -10 \text{ mA}, V_{GS} = 20 \text{ V}$	-15	_	_	V
Gate threshold ve	oltage	V _{th}	$V_{DS} = -10 \text{ V}, I_D = -1 \text{ mA}$	-0.8	_	-2.0	٧
Drain-source ON	recistance	Pro (ON)	$V_{GS} = -4.5 \text{ V}, I_D = -1.6 \text{A}$		80	105	mΩ
Dialii-source ON	resistance	R _{DS} (ON)	$V_{GS} = -10 \text{ V}, I_D = -1.6 \text{ A}$	_	60	72	11152
Forward transfer	admittance	Y _{fs}	$V_{DS} = -10 \text{ V}, I_D = -1.6 \text{ A}$	2.9	5.9	_	S
Input capacitance		C _{iss}	V _{DS} = -10 V, V _{GS} = 0 V, f = 1 MHz	_	600	_	pF
Reverse transfer capacitance		C _{rss}		_	60	_	
Output capacitance		Coss		_	70	_	
	Rise time	t _r	$V_{GS} \stackrel{0\ V}{\underset{-10}{\longrightarrow}} \stackrel{I_{D}\ =\ -1.6\ A}{\underset{N}{\longrightarrow}} V_{DD} \approx -15\ V$ Duty \leq 1%, t_{W} = 10 μs	_	5.3	_	
Switching time	Turn-on time	t _{on}		_	12	_	200
Switching time	Fall time	t _f		_	8.4	_	ns
	Turn-off time	t _{off}		_	34	_	
Total gate charge (gate-source plus gate-drain)		Qg	V _{DD} ≈ -24 V, V _{GS} = -10 V,	_	14	_	
Gate-source charge 1		Q _{gs1}	$I_D = -3.2 \text{ A}$		1.4	_	nC
Gate-drain ("miller") charge		Q _{gd}		_	2.7		

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I _{DRP}	_	_	_	-12.8	Α
Forward voltage (diode)		V_{DSF}	$I_{DR} = -3.2 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	1.2	V

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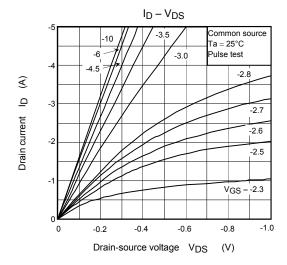


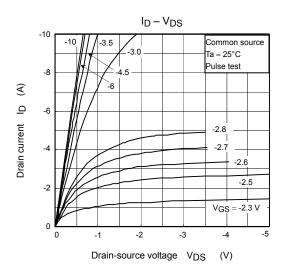
Electrical Characteristics (Ta = 25°C)

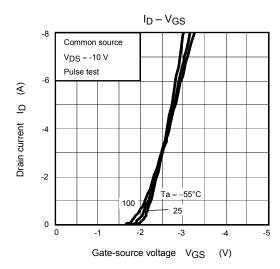
Cha	aracteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μA
Drain cut-off curre	ent	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V	_	_	10	μA
Drain-source brea	akdown	V _{(BR) DSS}	I _D = 10 mA, V _{GS} = 0 V	30	_	_	V
voltage		V _{(BR) DSX}	I _D = 10 mA, V _{GS} = -20 V	15	_	_	V
Gate threshold vo	oltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	1.3	_	2.5	V
Drain-source ON	registance	D	V _{GS} = 4.5 V, I _D = 2.0 A	_	58	77	mΩ
Drain-source ON	resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 2.0 A	_	38	50	
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 2.0 A	3.4	6.8	_	S
Input capacitance		C _{iss}		_	470	_	pF
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	60	_	
Output capacitan	ce	Coss		_	80	_	1
	Rise time	t _r	$V_{GS} \stackrel{10 \text{ V}}{\underset{O \text{ V}}{\text{ V}}} \stackrel{I_D = 2.0 \text{ A}}{\underset{S}{\text{ V}}} \stackrel{\text{O} \text{ V}}{\underset{S}{\text{ V}}} \stackrel{\text{O} \text{ V}}{\underset{S}} \stackrel{\text{O} \text{ V}}{\underset{S}{\text{ V}}} \stackrel{\text{O} \text{ V}}{\underset{S}} \stackrel{\text{O} \text{ V}}{$	_	5.2	_	
Switching time	Turn-on time	t _{on}		_	8.3	_	
Switching time	Fall time	t _f		_	4.0	_	- ns
	Turn-off time	t _{off}		_	22	_	
Total gate charge (gate-source plus gate-drain)		Qg		_	10	_	nC
Gate-source charge 1		Q _{gs1}	$V_{DD} \approx 24 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 4 \text{ A}$	_	1.7	_	
Gate-drain ("miller") charge		Q _{gd}		_	2.4	_	

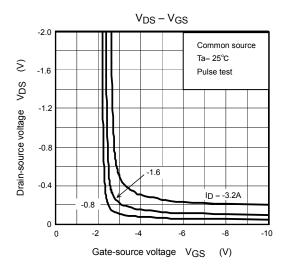
Source-Drain Ratings and Characteristics (Ta = 25°C)

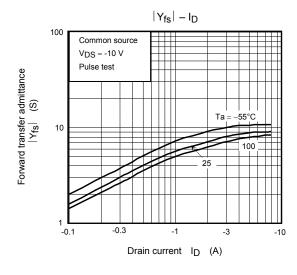
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I _{DRP}	_	_	_	16.0	Α
Forward voltage (diode)		V _{DSF}	I _{DR} = 4.0 A, V _{GS} = 0 V			-1.2	V

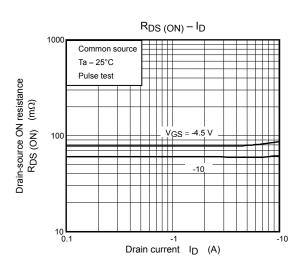


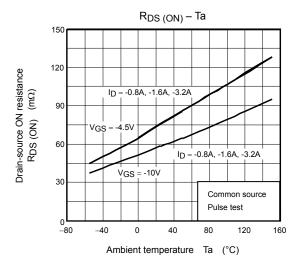


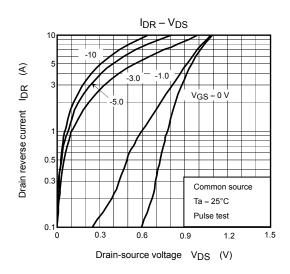


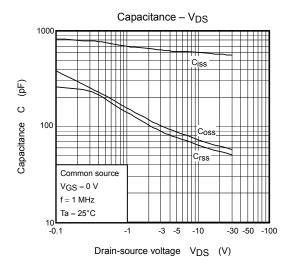


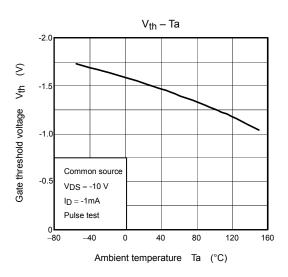


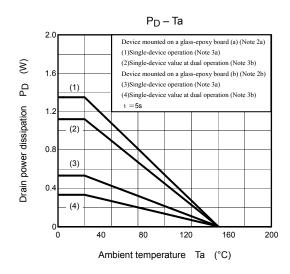


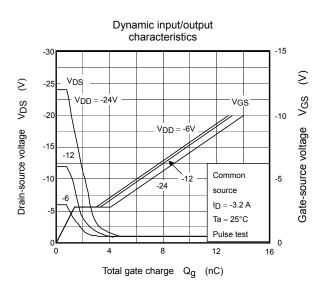


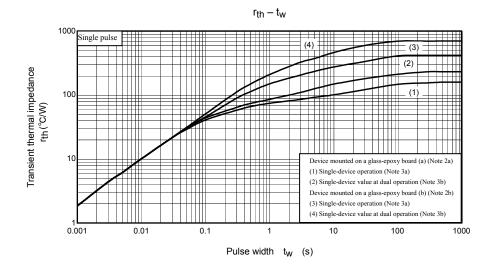


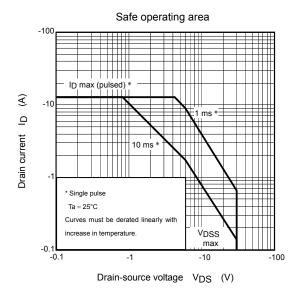


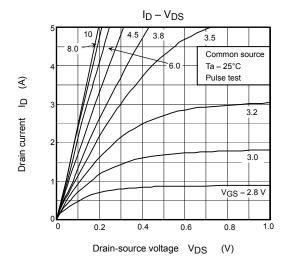


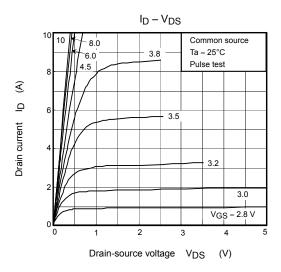


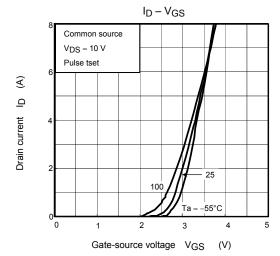


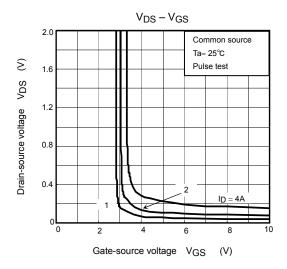


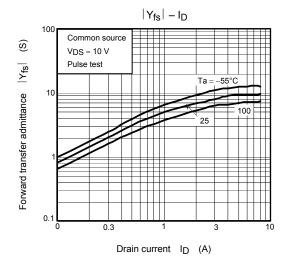


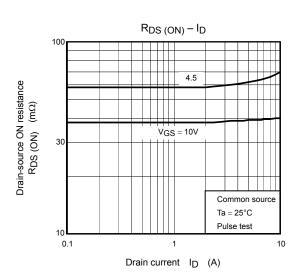


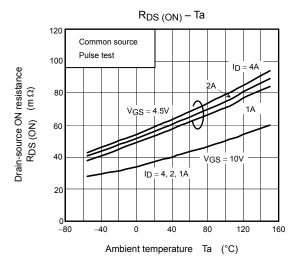


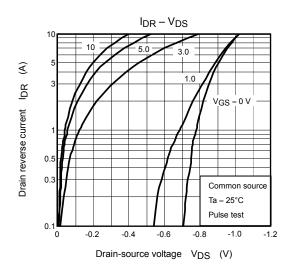


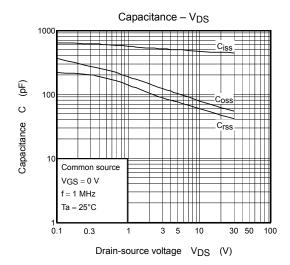


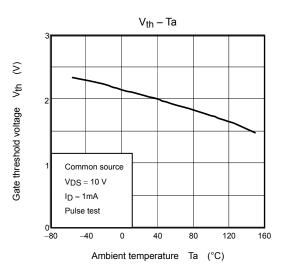


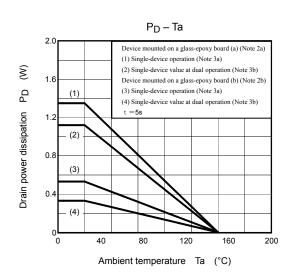


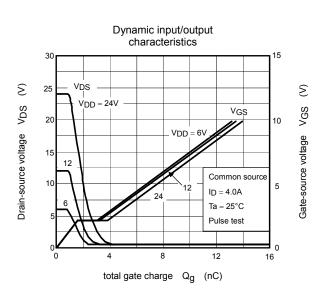


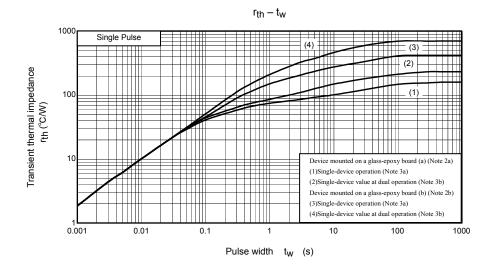


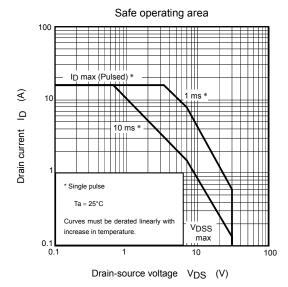












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